ABSTRACT OF THE DISCLOSURE

MULTI-CHIP CHIP SCALE PACKAGE

A multi-chip chip scale package. A film carrier is in use. Two chips with different sizes can be disposed on the same film carrier. The flip chip technique is used to arrange each chip on each side of the film carrier face to face. A bump is formed on each chip to electrically connect with the film carrier. An insulation material is infilled between the chips to leave one side of each chip exposed. The conductive wires of the film carrier are connected with the chip directly without going through other carrier.

Figure 3

This Sheet Has Been Replaced

